

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5043137

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JIANFENG SHAN	07/03/2018
RECEIVING PARTY DATA	
Name:	HKC CORPORATION LIMITED
Street Address:	5TH AND 7TH FLOOR OF FACTORY BUILDING 1, JIUZHOU YANGGUANG, FACTORY BUILDINGS 1, 2, 3 OF HKC INDUSTRIAL PARK, PRIVATELY OPERATED INDUSTRIAL PARK, SHUITIAN VILLAGE, SHIYAN SUB-DISTRICT, BAO'AN DISTRICT,
City:	SHENZHEN CITY, GUANGDONG
State/Country:	CHINA
Postal Code:	518000
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16068419
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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NAME OF SUBMITTER:	JOE MCKINNEY MUNCY
SIGNATURE:	/Joe McKinney Muncy/
DATE SIGNED:	07/10/2018
Total Attachments: 2	
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COMBINED DECLARATION AND ASSIGNMENT FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76)

Title of Invention | SHIFT REGISTER CIRCUIT AND DISPLAY PANEL USING THE SAME

As the below named inventor(s), I/We hereby declare that:

This Declaration and Assignment are directed to:

- The attached application; or
- United States application or PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me/us.

I/We believe that I/we are the original inventor or original joint inventors of a claimed invention in the application.

I/We am aware of and acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, §1.56

WHEREAS, HKC Corporation Limited, whose post office address is 5th and 7th Floor of Factory Building 1, Jiuzhou Yangguang, Factory Buildings 1, 2, 3 of HKC Industrial Park, Privately Operated Industrial Park, Shuitian Village, Shiyao Sub-district, Bao'an District, Shenzhen City, Guangdong 518000, China (hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire right, title and interest in and to the same in the United States and throughout the world;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I/we, the below named inventor(s) and collectively referred to hereinafter as ASSIGNOR, by these presents do sell, assign and transfer until said ASSIGNEE, the entire right, title and interest in and to said invention and application throughout the United States of America, including any and all United States Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application; and the entire right, title and interest in and to said invention throughout the world, including the right to apply for patents and inventor certificates in respect thereof and to claim priority pursuant to rights accorded ASSIGNOR under the terms of the Paris International Convention and all other available international conventions and treaties; and the entire right, title and interest in and to any and all patents, patents of addition, utility models, patents of importation, revalidation patents and inventor certificates which may be granted throughout the world in respect of said invention.

I/we here by agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) or inventor certificate(s) in the United States and in foreign countries for said invention, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said invention, all without further consideration. I/we also agree, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the invention that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

I/we hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent referred to above to ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behalf; and for the use and behalf of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

HKC170355-HZSZ2017249I-US-KS12017428PCT(CN)-US/CN-034

Please recognize or change the correspondence address for the application identified in the attached transmittal letter or the boxes above to:

The address associated with Customer Number: 60601
OR

Firm or Individual Name			
Address			
City	State	Zip	
Country			
Telephone			Email

I/We the undersigned hereby declare that all statements made herein and above of my/our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine, or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

INVENTOR/ASSIGNOR 1

FULL LEGAL NAME: SHAN, Jianfeng	ADDRESS 5th and 7th Floor of Factory Building 1, Jiuzhou Yangguang, Factory Buildings 1, 2, 3 of HKC Industrial Park, Privately Operated Industrial Park, Shuitian Village, Shiyan Sub-district, Bao'an District, Shenzhen City, Guangdong 518000, China
SIGNATURE SHAN Jianfeng	DATE 2018/7/3

INVENTOR/ASSIGNOR 2

FULL LEGAL NAME:	ADDRESS
SIGNATURE	DATE

Additional pages of signatures of joint inventors/assignees are attached.